

Day : Tuesday
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Time: 12:47:03

PALM INTRANET**Inventor Name Search Result**

Your Search was:

Last Name = WANG

First Name = TSUNG-HSIUNG

This case

Application#	Patent#	Status	Date Filed	Title	Inventor Name 7
<u>10083366</u>	Not Issued	060	02/27/2002	METHOD OF ENHANCEMENT OF ELECTRICAL CONDUCTIVITY FOR CONDUCTIVE POLYMER BY USE OF FIELD EFFECT CONTROL	WANG, TSUNG-HSIUNG
<u>09312303</u>	Not Issued	071	05/14/1999 N/D	BUMPLESS FLIP CHIP PACKAGE AND METHOD FOR FABRICATING	WANG, TSUNG-HSIUNG
<u>09312288</u>	<u>6204089</u>	150	05/14/1999 N/D	METHOD FOR FORMING FLIP CHIP PACKAGE UTILIZING CONE SHAPED BUMPS	WANG, TSUNG-HSIUNG
<u>09044969</u>	<u>6119338</u>	150	03/19/1998 N/D	METHOD FOR MANUFACTURING HIGH-DENSITY MULTILAYER PRINTED CIRCUIT BOARDS	WANG, TSUNG-HSIUNG
<u>07898008</u>	<u>5268432</u>	150	06/16/1992 N/D	HEAT RESISTANT MODIFIED BISMALEIMIDE ADHESIVE COMPOSITION	WANG, TSUNG-HSIUNG
<u>07821632</u>	<u>5342736</u>	150	01/16/1992 N/D	METHOD OF WET ETCHING OF POLYIMIDE	WANG, TSUNG-HSIUNG
<u>07790260</u>	<u>5217599</u>	150	11/08/1991 N/D	BONDING OF POLYIMIDE FILM	WANG, TSUNG-HSIUNG

Inventor Search Completed: No Records to Display.

Search Another: Inventor	Last Name	First Name
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Day : Tuesday
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PALM INTRANET**Inventor Name Search Result**

Your Search was:

Last Name = PAN

First Name = JING-PIN

Application#	Patent#	Status	Date Filed	Title	Inventor Name 22
<u>10378603</u>	Not Issued	071	03/05/2003 N/0	STRUCTURE OF AN INTERLEAVING STRIPED CAPACITOR SUBSTRATE	PAN, JING-PIN
<u>10162400</u>	Not Issued	095	06/05/2002 N/0	COMPOSITION OF BARBITURIC ACID-MODIFIED BMI AND PPE CHAIN BROKEN IN PHENOL RESIN	PAN, JING-PIN
<u>10083366</u>	Not Issued	060	02/27/2002	METHOD OF ENHANCEMENT OF ELECTRICAL CONDUCTIVITY FOR CONDUCTIVE POLYMER BY USE OF FIELD EFFECT CONTROL	PAN, JING-PIN
<u>09917753</u>	6562420	150	07/31/2001 N/0	LIQUID CRYSTAL ALIGNING FILM	PAN, JING-PIN
<u>09866727</u>	6432613	150	05/30/2001 N/0	PHOTOSENSITIVE COMPOSITION	PAN, JING-PIN
<u>09628061</u>	6359039	150	07/25/2000 N/0	MIXING BARBITURIC ACID-MODIFIED BMI WITH MEK SOLUTION OF EPOXY RESIN AND ELASTOMER	PAN, JING-PIN
<u>09292873</u>	6166322	150	04/16/1999 N/0	ENCAPULATION FOR MONO- AND POLYCRYSTALLINE SILICON SOLAR CELL MODULES	PAN, JING-PIN
<u>09253836</u>	6117951	150	02/19/1999 N/0	POLYIMIDE COMPOSITION FOR LOC ADHESIVE TAPE	PAN, JING-PIN
<u>09240797</u>	6340516	150	01/30/1999 N/0	INK JET RECORDING MATERIALS	PAN, JING-PIN
<u>09067972</u>	Not Issued	161	04/28/1998 N/0	HIGH-PERFORMANCE ADHESIVE COMPOSITIONS	PAN, JING-PIN
<u>08998685</u>	5928789	150	12/29/1997 N/0	INK JET PRINTING MEDIUM	PAN, JING-PIN

08907570	Not Issued	163	08/08/1997	ENCAPULATION PROCESS FOR MONO- AND POLYCRYSTALLINE SILICON SOLAR CELL MODULES	PAN , JING-PIN
08302570	5518779	150	09/08/1994 N)	FORMING COPPER CLAD LAMINATES	PAN , JING-PIN
08198352	5418066	250	02/18/1994 μ)	POLYIMIDE COMPOSITION FOR POLYIMIDE/COPPER FOIL LAMINATE	PAN , JING-PIN
08089797	5602213	150	07/09/1993 N)	HEAT RESISTANT COMPOSITION BISMALEIMIDE-MODIFIED POLYURETHANE	PAN , JING-PIN
08070537	5290909	150	05/28/1993 N)	POLYIMIDE COMPOSITION FOR POLYIMIDE/COPPER FOIL LAMINATE	PAN , JING-PIN
07991287	5372891	150	12/16/1992 N)	A FLEXIBLE COPPER/POLYIMIDE AND BARBITURIC ACID MODIFIED BISMALEIMIDE BLEND/ POLYIMIDE LAMINATE	PAN , JING-PIN
07966738	5310850	250	10/26/1992 N)	HEAT RESISTANT POLY (URETHANE AMIDEIMIDE) COMPOSITION AND METHOD FOR PREPARING THE SAME	PAN , JING-PIN
07911692	5326794	150	07/10/1992 N)	BARBITURIC ACID-MODIFIED BISMALEIMIDE WITH DIAMINE AND POLYISOCYANATE-MODIFIED EPOXY RESIN	PAN , JING-PIN
07898008	5268432	150	06/16/1992 N)	HEAT RESISTANT MODIFIED BISMALEIMIDE ADHESIVE COMPOSITION	PAN , JING-PIN
07827591	5225250	150	01/29/1992 N)	METHOD OF IMPREGNATING USING A FLOATING BLADE	PAN , JING-PIN
07281069	5041519	150	12/08/1988 N)	COMPOSITION COMPRISING EPOXY RESIN, BISMALEIMIDE AND BARBITURIC ACID	PAN , JING-PIN

Inventor Search Completed: No Records to Display.

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2	L7	13648 6	(conductive adj (polymer plastic monomer dimer oligmer) polyaniline polypyrrole polythiophene aniline pyrrole thiophene)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/06/0 1 09:22
3	L8	82	6 and 7	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/06/0 1 09:22
4	L9	24	8 and (plasma same microwave)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/06/0 1 09:23

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5	L10	115	(plasma same microwave) and(conductive adj (polymer plastic monomer dimer oligmer) polyaniline polypyrrole polythiophene) not 9	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/06/0 1 09:24